



AF/2800

Attorney Docket SEL 173

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of
Ohtani et al.
Serial No.: 09/535,836
Filed: March 28, 2000
For: Semiconductor Device Having
Multi-layer Wiring
Art Unit: 2811
Examiner: H. Vu

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Commissioner for Patents
Washington, D.C. 20231

AMENDMENT C (AFTER FINAL)

Sir:

In response to the Final Rejection dated January 7, 2002, please enter the following amendment in the above-identified application.

IN THE CLAIMS:

Please amend the claims as follows:

41. (Amended) The semiconductor device according to claim 40, wherein said first wiring is selected from the group consisting of aluminum and a material predominantly composed of aluminum.

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42. (Amended) The semiconductor device according to claim 40, wherein said second wiring is selected from the group consisting of titanium and a material predominantly composed of titanium.